

ABSTRACT

Provided are a curable resin composition that can reduce the amount of warpage both at a temperature for mounting a semiconductor wafer or a semiconductor package, in particular, a fan-out wafer level package (FO-WLP) and at room temperature for, for example, conveying wafers, and a fan-out wafer level package that includes a warpage correction layer made of a cured product of the curable resin composition. The curable resin composition is curable through at least two types of curing reactions, and includes a curable component (A1) that contracts in volume through one curing reaction, and a curable component (B1) that contracts in volume through another curing reaction.